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Optimization of process parameters for the chemical leaching of base

metals from telecom and desktop printed circuit boards

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Highlights

- An increase in H₂SO₄ or H₂O₂ concentration enhanced the leaching of Cu, Ni and Zn
- Cu dissolution increased at low pulp density, small particle size and H₂O₂ addition
- Stirred tank reactor showed higher leaching efficiencies of metals than the upflowcolumn

Abstract

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